



PNP Transistor Bare Die, MPSA55

Rev 1.1
27/03/21

General purpose high voltage amplifier in bare die form
Complement to NPN MPSA05

Features:

- 60 Volt V_{CE0}
- Low $V_{CE(sat)}$
- Characterized at temperature extremes
- High Reliability Gold Back Metal
- High Reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

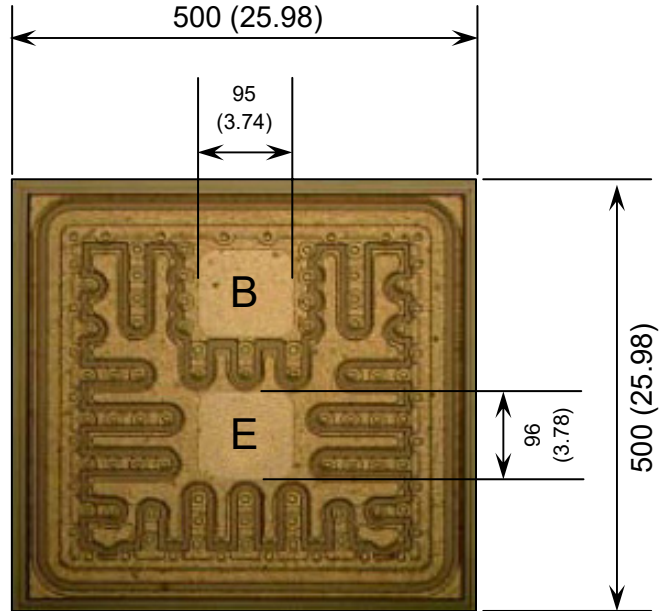
- No suffix - MIL-STD-750 /2072 Visual Inspection
- "H" - MIL-STD-750 /2072 Visual Inspection
+ MIL-STD-38534 Class H LAT
- "K" - MIL-STD-750 /2072 Visual Inspection
+ MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

www.siliconsupplies.com/quality/bare-die-lot-qualification

Die Dimensions in μm (mils)



E = EMITTER B = BASE

DIE BACK = COLLECTOR

Supply Formats:

- Default – Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape – Specific request
- Unsawn Wafer – Specific request
- With additional electrical selection – Specific request
- Sawn as pairs or adjacent pair pick – Specific request

Mechanical Specification

Die Size (Excluding Saw Street)	500 x 500 19.69 x 19.69	μm mils
Base & Emitter Pad Size	95 x 96 3.74 x 3.78	μm mils
Die Thickness	180 (± 20) 7.09 (± 0.79)	μm mils
Top Metal Composition	Al - 2.6 μm	
Back Metal Composition	AuAs - 0.9 μm	





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Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V_{CBO}	-60	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-4	V
Collector Current	I_C	-500	mA
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to 150	$^\circ\text{C}$

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C = -100\mu\text{A}$	-60	-	-	V
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C = -1\text{mA}$	-60	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E = -100\mu\text{A}$	-5	-	-	V
Collector Cut-off Current	I_{CBO}	$V_{CB} = -60\text{V}$	-	-	-100	nA
Emitter Cut-off Current	I_{CEO}	$V_{EB} = -60\text{V}$	-	-	-100	nA
ON CHARACTERISTICS						
Forward-Current Transfer Ratio	h_{FE}	$V_{CE} = -1\text{V}, I_C = -10\text{mA}$	100	-	-	-
		$V_{CE} = -1\text{V}, I_C = -100\text{mA}$	100	-	-	-
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -100\text{mA}, I_B = -10\text{mA}$	-	-	-0.25	V
Base Saturation Voltage	$V_{BE(sat)}$	$I_C = -100\text{mA}, V_{CE} = -1\text{V}$	-	-	-1.2	V
SMALL SIGNAL CHARACTERISTICS¹						
Transition Frequency	f_T	$V_{CE} = -1\text{V}, I_C = -100\text{mA}, f = 100\text{MHz}$	50	70	-	MHz
Output Capacitance	C_{obo}	$V_{CB} = -20\text{V}, I_E = 0, f = 1\text{MHz}$	-	3.5	-	pF

Note 1: Not production testing in die form. Characterized by chip design and tested in package LAT.

Typical Electrical Characteristics

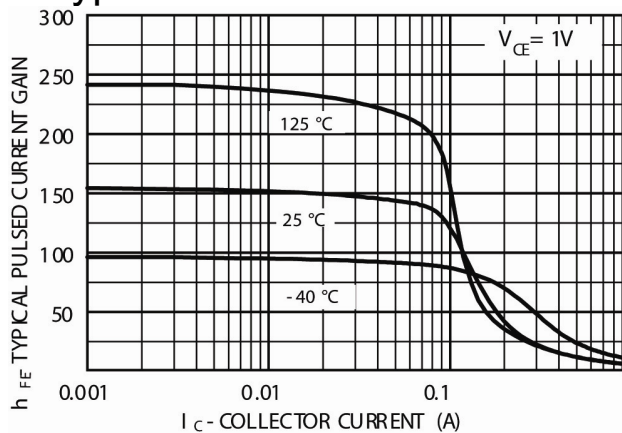


Fig 1 - Typical Pulsed Current Gain versus Collector Current

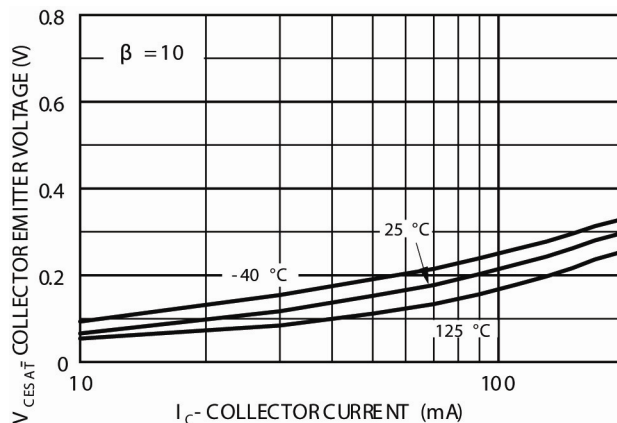


Fig 2 - Collector-Emitter Saturation Voltage versus Collector Current





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Rev 1.1
27/03/21

Typical Electrical Characteristics (Continued)

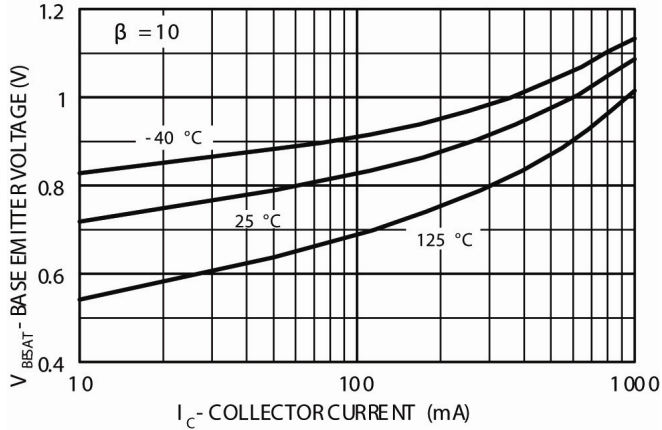


Fig 3 - Base-Emitter Saturation Voltage versus Collector Current

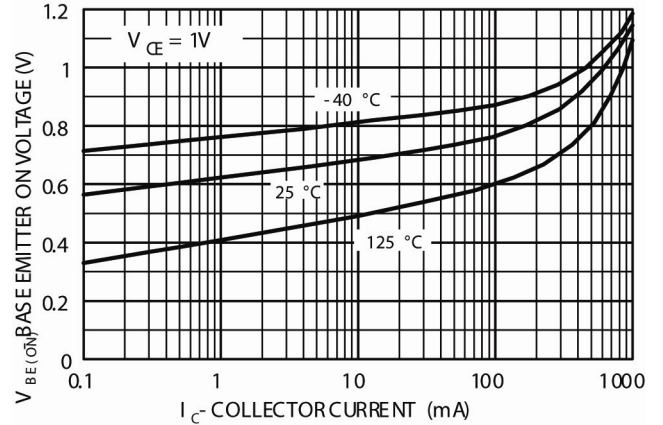


Fig 4 - Base-Emitter ON Voltage versus Collector Current

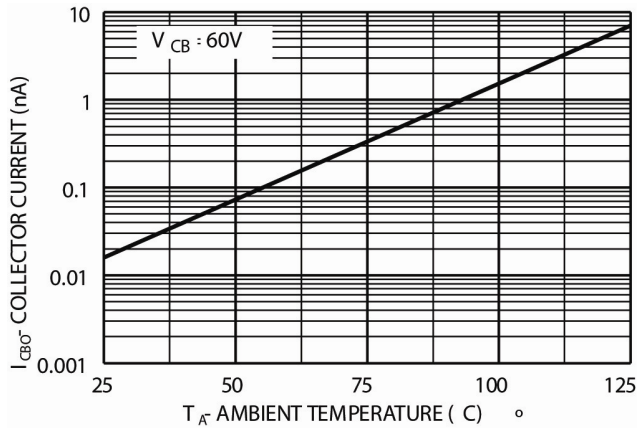


Fig 5 - Collector-Cut-off Current versus Ambient Temperature

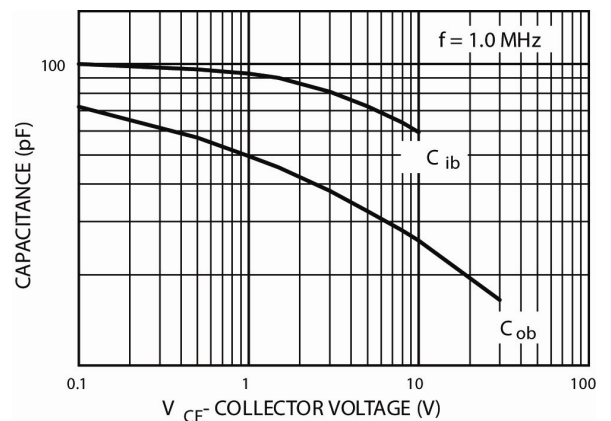


Fig 6 - Input and Output Capacitance versus Reverse Voltage

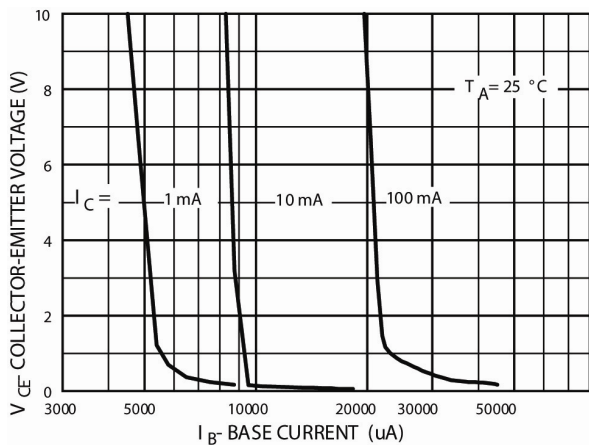


Fig 7 - Collector Saturation region

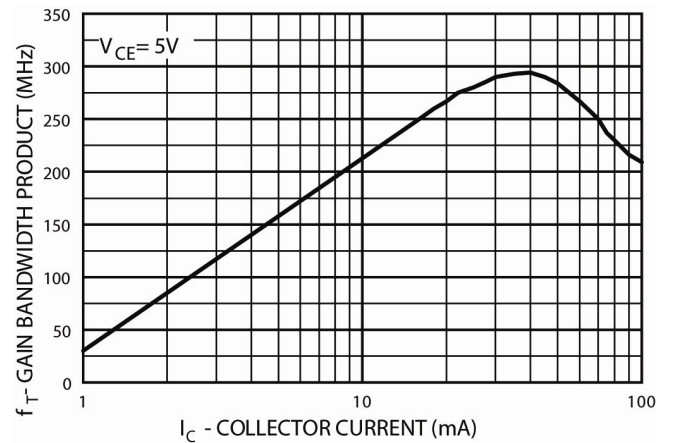


Fig 8 - Gain Bandwidth Product versus Collector Current





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